









CEM6608

60V ▲ 60mΩ ▲ 4A ▲ Dual Si MOSFET

SILICON Si MOSFET ▲ SMD type
Dual N-channel enhancement mode
UL94V-0 rated flame retardant epoxy
SO8 package ▲ MSL 3

Super high dense cell density for extremely low R_{DS(ON)} **High power and current handling capability**

MAXIMUM RATINGS

Parameter (T _A = 25°C, unless otherwise noted)	Characteristics	
Drain-Source Voltage	V _{DS}	60V
Gate-Source Voltage	V _{GS}	±20V
Continuous Drain Current	I _D	4A
Pulsed Drain Current Note 1	I _{DM}	15A
Maximum Power Dissipation	P _D	2W
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

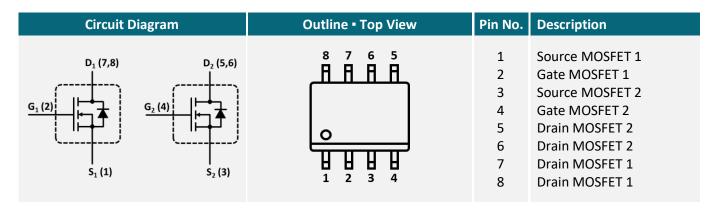
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Ambient Note 2	R _{TH_JA}	62.5°C/W

APPLICATIONS

Audio	Battery Management Systems	DC/DC	Industrial	Power
Amplifier		Converter	Control	Switches
	+ 4 -			

PIN DESCRIPTION





ELECTRICAL CHARACTERISTICS ▲ T_A = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$	BV_DSS	60			V
Zero Gate Voltage Drain Current	$V_{DS} = 60V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	I _{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -20V, V_{DS} = 0V$	I _{GSSR}			-100	nA
On Characteristics Note 3						
Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	$V_{GS(th)}$	1		3	V
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 4A$	R _{DS(ON)}		60	76	mΩ
Static Drain-Source On-Resistance	$V_{GS} = 4.5V$, $I_D = 3.4A$	R _{DS(ON)}		80	100	mΩ
Dynamic Characteristics Note 4						
Forward Transconductance	$V_{DS} = 10V, I_{D} = 4A$	g FS		10		S
Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		415		pF
Output Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$ C_{OSS}			123		pF
Reverse Transfer Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz C_{RSS}			33		pF
Switching Characteristics Note 4						
Turn-On Delay Time	$V_{DD} = 30V$, $V_{GS} = 10V$, $I_{D} = 1A$, $R_{G(ext)} = 6\Omega$	t _{D(ON)}		9	18	ns
Turn-On Rise Time	V_{DD} = 30V, V_{GS} = 10V, I_D = 1A, $R_{G(ext)}$ = 6Ω	t _R		2.5	5	ns
Turn-Off Delay Time	$V_{DD} = 30V$, $V_{GS} = 10V$, $I_{D} = 1A$, $R_{G(ext)} = 6\Omega$	t _{D(OFF)}		30	60	ns
Turn-Off Fall Time	V_{DD} = 30V, V_{GS} = 10V, I_D = 1A, $R_{G(ext)}$ = 6Ω	t _F		4	8	ns
Total Gate Charge	$V_{DS} = 30V$, $V_{GS} = 10V$, $I_{D} = 4A$	Q_{G}		12	16	nC
Gate Source Charge	$V_{DS} = 30V$, $V_{GS} = 10V$, $I_{D} = 4A$	Q _{GS}		1.1		nC
Gate Drain Charge	$V_{DS} = 30V, V_{GS} = 10V, I_D = 4A$	Q_{GD}		3		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode Forward Current Note 2	_	Is			1.6	Α
Drain-Source Diode Forward Voltage Note 3	$V_{GS} = 0V$, $I_S = 1.6A$	V_{SD}			1.2	V

Notes

1: Repetitive Rating: Pulse width limited by maximum junction temperature

2: Surface Mounted on FR4 Board, t ≤ 10 sec

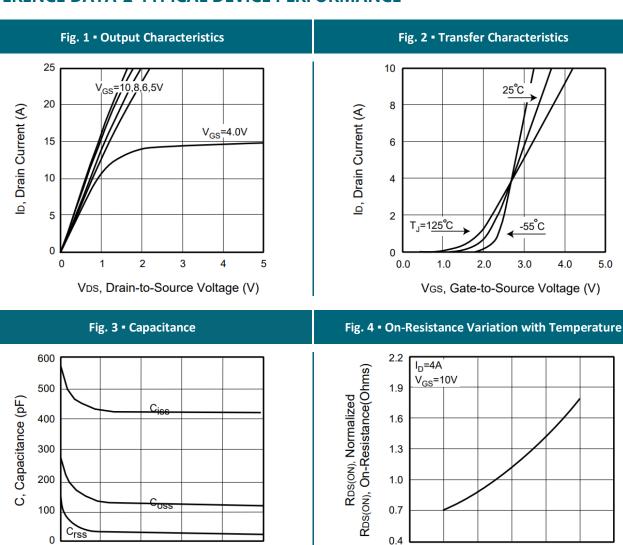
3: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

4: Guaranteed by design, not subject to production testing.

5.0



REFERENCE DATA A TYPICAL DEVICE PERFORMANCE





10

15

VDS, Drain-to-Source Voltage (V)

20

25

5

0

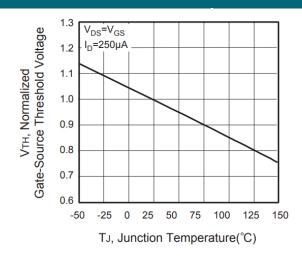


Fig. 6 • Body Diode Forward Voltage Variation with Source Current

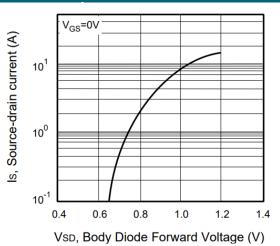
T_J, Junction Temperature(°C)

100

150

200

-100



MGT ▲ Manufacturer Group of Technology



REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

Fig. 7 • Gate Charge

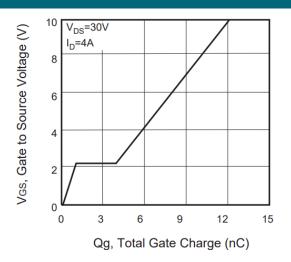


Fig. 8 • Maximum Safe Operating Area

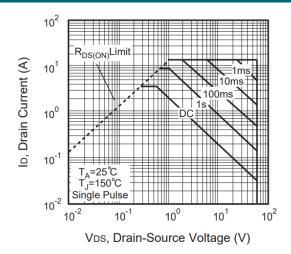


Fig. 9 • Breakdown Voltage Variation vs. Temperature

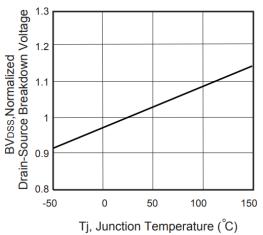
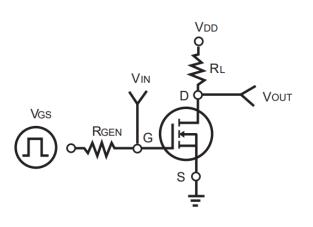
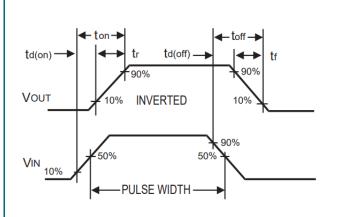


Fig. 10 • Switching Test Circuit

Fig. 11 • Switching Waveforms

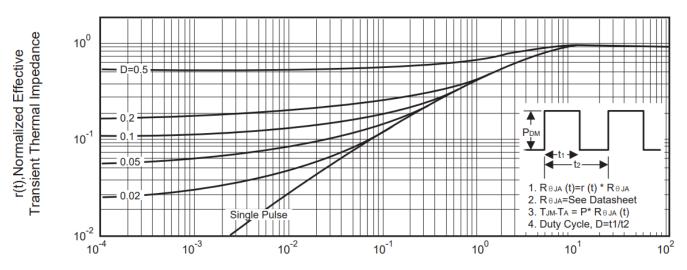






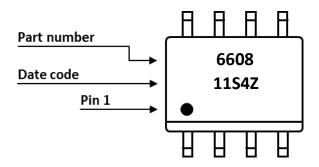
REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

Fig. 12 • Normalized Thermal Transient Impedance Curve



Square Wave Pulse Duration (sec)

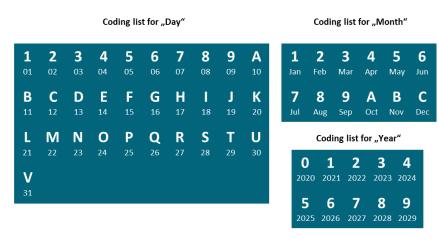
PART MARKING



DATE CODE

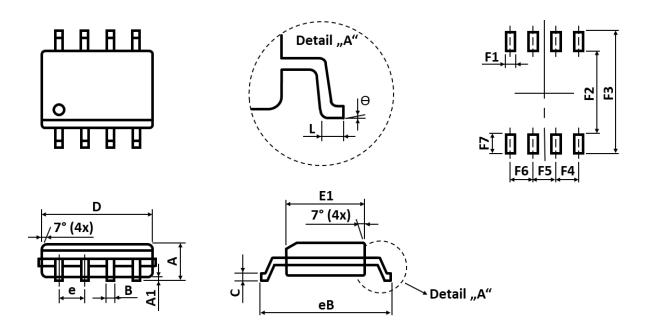
Example: 11S4Z







PACKAGE OUTLINE AND RECOMMENDED PAD LAYOUT



Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	1.350	-	1.750
A1	0.100	-	0.250
В	0.310	-	0.510
С	0.170	-	0.250
D	4.690	-	5.000

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
E1	3.700		4.060
еВ	5.800		6.200
е		1.270	
L	0.400		0.950
Θ	0°	-	8°

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
F1	-	0.500	-
F2	-	4.250	-
F3	-	6.250	-
F4	-	1.270	-

Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
-	1.270	-
-	1.270	-
-	1.000	-
		- 1.270 - 1.270

Notes: 1. The suggested land pattern dimensions have been provided for reference only.

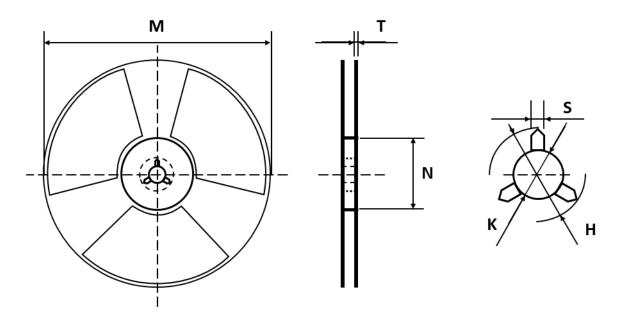
2. For further information, please reference document IPC-7351A.

ORDERING INFORMATION

Part Number	Package	Packing	Reel Qty.	Inner Box Qty.	Outer Box Qty.
CEM6608	SO8	13" Reel	2,500pcs	5,000pcs	40,000pcs

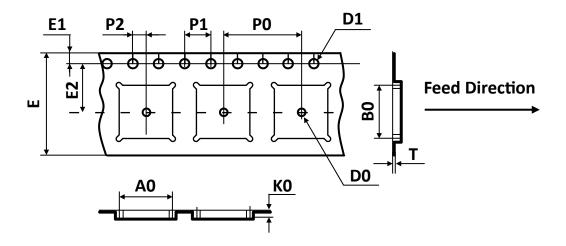


REEL DIMENSIONS ▲ All dimensions in mm



Tape Size	Reel Size	M	N	Т	Н	K	S
12mm	Ø330	Ø330.00	Ø100.00	2.20	20.00	13.20	3.00
	<i>y</i> 550	±2.00	±0.50	±0.20	±1.00	±0.20	±1.00

TAPE DIMENSIONS ▲ All dimensions in mm

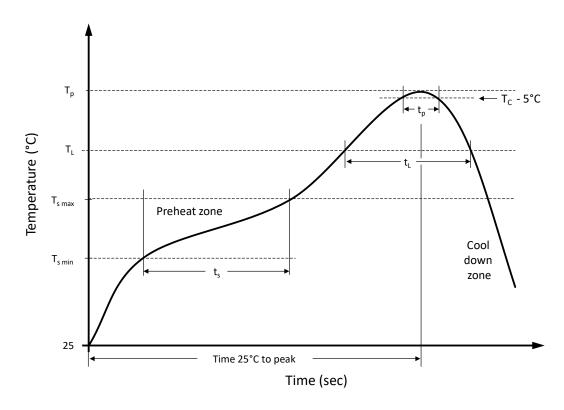


Package	Α0	В0	КО	D0	D1	E	E1	E2	P0	P1	P2	T
SO8	6.50	5.30	2.05	1.50	1.50	12.00	1.75	5.50	8.00	4.00	2.00	0.25
308	±0.10	±0.10	±0.15	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05	±0.02

Note: All dimensions meet EIA-481-D requirements.



RECOMMENDED REFLOW SOLDERING PROFILE



Recommended reflow soldering conditions ▲ **Refer to JEDEC J-STD-020E**

Profile Features		Sn-Pb Eutetic Assembly	Pb-Free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	150 °C
Preheat temperature max.	T _{s max}	150 °C	200 °C
Preheat time t _s from T _{s min} to T _{s max}	ts	120 seconds	120 seconds
Ramp-up rate (T₁ to Tp)		max. 3 °C/second	max. 3 °C/second
Liquidous temperature	T_L	183 °C	217 °C
Time t _L maintained above T _L	t _L	150 seconds max.	150 seconds max.
Peak package body temperature	Tp	235°C	260°C
Timeframe of within 5°C below and up to max actual peak body temperature	t _p	20 seconds max.	30 seconds max.
Ramp-down rate (T _L to T _p)		max. 6 °C/second	max. 6 °C/second
Time 25°C to peak temperature		max. 6 minutes	max. 8 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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